



# **Dual N-Channel 30-V (D-S) MOSFET**

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a, e</sup>	Q <sub>g</sub> (Typ.)			
	0.016 at V <sub>GS</sub> = 10 V	8				
30	0.018 at V <sub>GS</sub> = 4.5 V	8	19			
	0.024 at V <sub>GS</sub> = 2.5 V	8				

## **Definition** TrenchFET® Power MOSFET 100 % $R_g$ and UIS tested

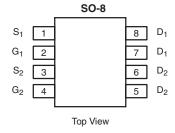
**FEATURES** 

Compliant to RoHS Directive 2002/95/EC

Halogen-free According to IEC 61249-2-21

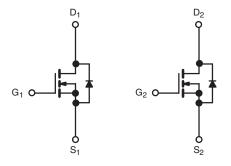






Ordering Information: Si4922BDY-T1-E3 (Lead (Pb)-free)

Si4922BDY-T1-GE3 (Lead (Pb)-free and Halogen-free)



N-Channel MOSFET

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T	$_{A}$ = 25 $^{\circ}$ C, unless other	erwise noted		
Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	30	V	
Gate-Source Voltage	V <sub>GS</sub>	± 12	v	
	T <sub>C</sub> = 25 °C		8 <sup>e</sup>	
Continuous Drain Current (T <sub>.I</sub> = 150 °C)	T <sub>C</sub> = 70 °C		8 <sup>e</sup>	
Continuous Diam Curient (1) = 130 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	8 <sup>b, c, e</sup>	
	T <sub>A</sub> = 70 °C		6.6 <sup>b, c</sup>	
Pulsed Drain Current (10 μs Pulse Width)		I <sub>DM</sub>	35	А
Source-Drain Current Diode Current	T <sub>C</sub> = 25 °C	I.	2.5	
Source-Dialit Current blode Current	T <sub>A</sub> = 25 °C	ls –	1.7 <sup>b, c</sup>	
Pulsed Sorce-Drain Current	I <sub>SM</sub>	35		
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	15	
Single-Pulse Avalanche Energy	L = 0.1 IIII1	E <sub>AS</sub>	11.2	mJ
	T <sub>C</sub> = 25 °C		3.1	
Maximum Power Dissipation	T <sub>C</sub> = 70 °C	P <sub>D</sub>	2	w
Maximum Fower Dissipation	T <sub>A</sub> = 25 °C	' b	2 <sup>b, c</sup>	VV
	T <sub>A</sub> = 70 °C		1.28 <sup>b, c</sup>	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 50 to 150	°C	

THERMAL RESISTANCE RATINGS						
		Lir	nit			
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient <sup>b, d</sup>	t ≤ 10 s	R <sub>thJA</sub>	50	62.5	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	R <sub>thJF</sub>	30	40	C/VV	

### Notes:

- a. Based on  $T_C = 25$  °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. t = 10 s.
- d. Maximum under Steady State conditions is 110 °C/W.
- e. Package Limited.

# Si4922BDY

# Vishay Siliconix



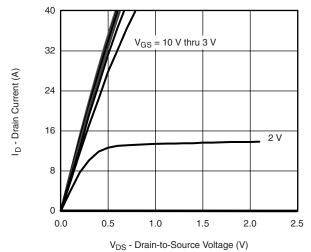
<b>SPECIFICATIONS</b> $T_J = 25  ^{\circ}C$ , UParameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static	Symbol	rest conditions	IVIIII.	тур.	IVIAA.	Unit	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30		1	V	
V <sub>DS</sub> Temperature Coefficient	ΔV <sub>DS</sub> /T <sub>J</sub>		- 00	35		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 250 μA		- 4.6			
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	0.6	7.0	1.8	V	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$	0.0		100	nA	
Care Body Learnage	.055	$V_{DS} = 30 \text{ V}, V_{GS} = 0 \text{ V}$			1	11/4	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 30 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 55 °C			10	μΑ	
On-State Drain Current <sup>b</sup>	I <sub>D(on)</sub>	V <sub>DS</sub> = 5 V, V <sub>GS</sub> = 10 V	20			Α	
		$V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$		0.0135	0.016		
Drain-Source On-State Resistance <sup>b</sup>	R <sub>DS(on)</sub>	$V_{GS} = 4.5 \text{ V}, I_D = 5 \text{ A}$		0.0145	0.018	Ω	
	` ´	$V_{GS} = 2.5 \text{ V}, I_D = 5 \text{ A}$		0.018	0.024		
Forward Transconductance <sup>b</sup>	9 <sub>fs</sub>	$V_{DS} = 15 \text{ V}, I_D = 5 \text{ A}$		30		S	
Dynamic <sup>a</sup>	•			l .			
Input Capacitance	C <sub>iss</sub>			2070		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		255			
Reverse Transfer Capacitance	C <sub>rss</sub>			135			
Total Cata Chausa		$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$		41	62	nC	
Total Gate Charge	$Q_g$			19	29		
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 5 \text{ A}$		3.5			
Gate-Drain Charge	$Q_{gd}$			3.7			
Gate Resistance	$R_{g}$	f = 1 MHz		1.8	3	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			7	14		
Rise Time	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, R_L = 3 \Omega$		27	41		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D\cong 5$ A, $V_{GEN}=10$ V, $R_g=1$ $\Omega$		31	47		
Fall Time	t <sub>f</sub>			8	15		
Turn-On Delay Time	t <sub>d(on)</sub>			13	25	ns	
Rise Time	t <sub>r</sub>	$V_{DD} = 15 \text{ V}, R_L = 3 \Omega$		53	80	1	
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 5 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		68	68 102		
Fall Time	t <sub>f</sub>			54	81		
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			2.5	A	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				35	_ A	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = 1.7 A		0.77	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			32	48	ns	
Body Diode Reverse Recovery Charge	$Q_{rr}$	1 1 7 A 41/44 100 A/45 T 05 00		21	32	nC	
Reverse Recovery Fall Time	t <sub>a</sub>	$I_F = 1.7 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		13			
Reverse Recovery Rise Time	t <sub>b</sub>	†		19		ns	

- a. Guaranteed by design, not subject to production testing.
- b. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.

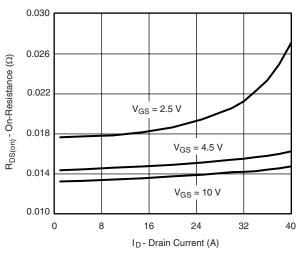
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



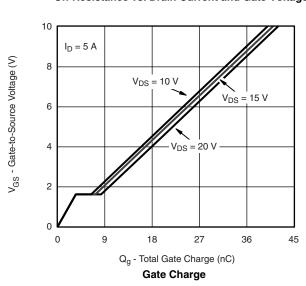
### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

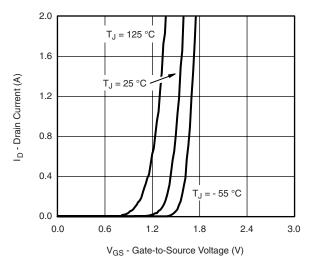




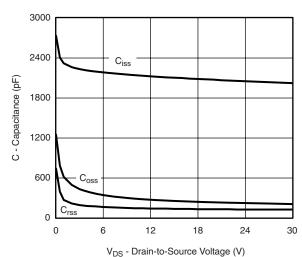


On-Resistance vs. Drain Current and Gate Voltage

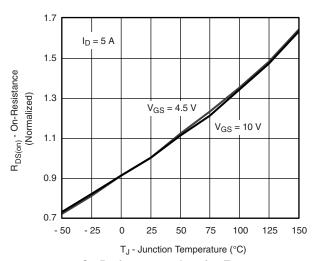




**Transfer Characteristics** 



Capacitance

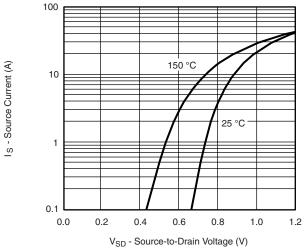


On-Resistance vs. Junction Temperature

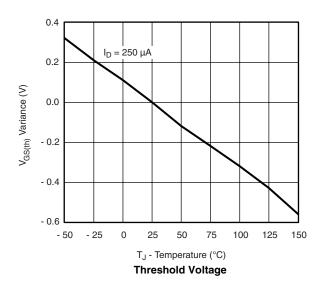
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### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

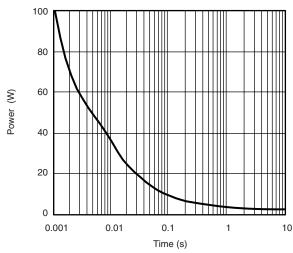


Source-Drain Diode Forward Voltage

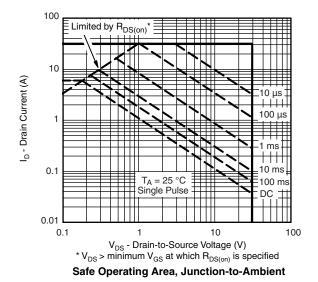


0.10 I<sub>D</sub> = 5 A 0.08  $\mathsf{R}_{\mathsf{DS}(\mathsf{on})}$  - On-Resistance  $(\Omega)$ 0.06 0.04 125 °C 0.02 25 °C 0.00 2 0 1 5 6 V<sub>GS</sub> - Gate-to-Source Voltage (V)

On-Resistance vs. Gate-to-Source Voltage

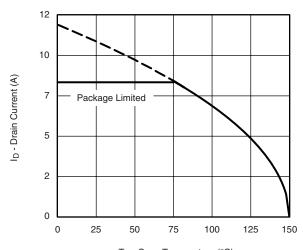


Single Pulse Power, Junction-to-Ambient



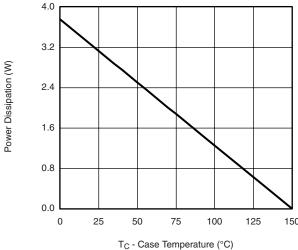


### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



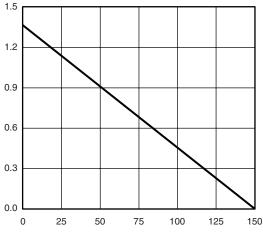
T<sub>C</sub> - Case Temperature (°C)

### **Current Derating\***









T<sub>A</sub> - Ambient Temperature (°C)

Power Derating, Junction-to-Ambient

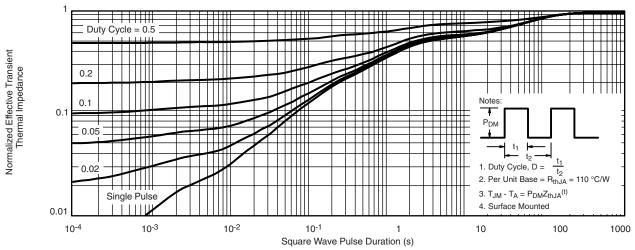
Power Derating, Junction-to-Foot

<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

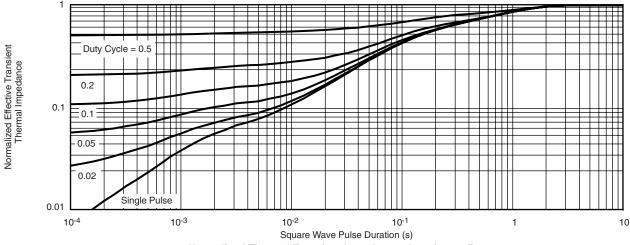
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### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg274459">www.vishay.com/ppg274459</a>.



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIM	IETERS	INCHES			
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A <sub>1</sub>	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
Е	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050	0.050 BSC		
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
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### **RECOMMENDED MINIMUM PADS FOR SO-8**



Recommended Minimum Pads Dimensions in Inches/(mm)

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